



DUAL P-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary (Typ. @ V_{GS} = -4.5V, T_A = +25°C)

V _{DSS}	R _{DS(on)}	Qg	Q_{gd}	Ι _D
-20V	80mΩ	3.3nC	0.6nC	-4A

Description

This new generation MOSFET is designed to minimize the on-state resistance $(R_{D1D2(ON)})$ and yet maintain superior switching performance, making it ideal for high-efficiency power management applications.

Applications

- Battery Management
- Load Switch
- Battery Protection

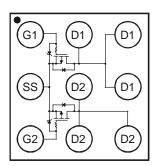


Features and Benefits

- LD-MOS Technology with the Lowest Figure of Merit: $R_{DS(on)} = 80 m\Omega \text{ to Minimize On-State Losses} \\ Q_{\alpha} = 3.3 nC \text{ for Ultra-Fast Switching}$
- $V_{gs(th)} = -0.7V$ typ. for a Low Turn-On Potential
- CSP with Footprint 1.5mm x 1.5mm
- Height = 0.62mm for Low Profile
- ESD = 3kV HBM Protection of Gate
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

- Case: U-WLB1515-9
- Terminal Connections: See Diagram Below
- Weight: 0.0018 grams (Approximate)



Top View

Ordering Information (Note 4)

Part Number	Case	Packaging
DMP2100UCB9-7	U-WLB1515-9	3,000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information

U-WLB1515-9

● 6W YM

6W = Product Type Marking Code YM = Date Code Marking Y = Year (ex: Y = 2011) M = Month (ex: 9 = September)

Date Code Key

Year	2012	2	2013		2014	20	15	2016		2017	2	2018
Code	Z		Α		В	(D		Е		F
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Units	
Drain-Source Voltage		V_{D1D2}	-20	V	
Gate-Source Voltage		V _{GS}	-6	V	
Continuous Drain Current (Note 5) V _{GS} = -4.5V	Steady State	T _C = +25°C T _C = +70°C	I _{D1D2}	-3.0 -2.1	А
Continuous Drain Current (Note 6) V _{GS} = -4.5V	Steady State	T _C = +25°C T _C = +70°C	I _{D1D2}	-4.0 -3.0	A
Continuous Source Pin Current (Note 6)		Is	-2.0	Α	
Continuous Gate Clamp Current (Note 6)		I _G	-0.4	Α	
Pulsed Source Pin Current (Pulse duration 10µs, d	uty cycle ≤	I _{SM}	-15	Α	
Pulsed Drain Current (Pulse duration 10µs, duty cy	rcle ≤ 1%)	I _{DM}	-28	Α	
Pulsed Gate Clamp Current (Pulse duration 10µs,	duty cycle :	≤ 1%)	I _{GM}	-6	А

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Units
Total Power Dissipation (Note 5)	P _D	0.8	W
Total Power Dissipation (Note 6)	P _D	1.6	W
Thermal Resistance, Junction to Ambient (Note 5)	R _{0JA}	152	°C/W
Thermal Resistance, Junction to Ambient (Note 6)	R ₀ JA	65	°C/W
Operating and Storage Temperature Range	T _{J,} T _{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

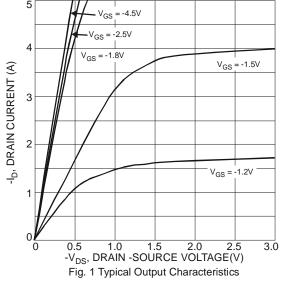
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						
Drain-Source Breakdown Voltage	BV _{D1D2}	-20	-	_	V	$V_{GS} = 0V, I_{D1D2} = -250\mu A$
Gate-Source Breakdown Voltage	BV_{GSS}	-6.1	_	_	V	$I_{GS} = -250 \mu A, V_{D1D2} = 0 V$
Zero Gate Voltage Drain Current @T _C = +25°C	I _{DDS}	_	-	-1	μA	$V_{D1D2} = -16V, V_{GS} = 0V$
Gate-Source Leakage	I_{GSS}	_	_	-100	nA	$V_{GS} = -6V$, $V_{DS} = 0V$
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	$V_{GS(th)}$	-0.4	-0.7	-0.9	V	$V_{D1D2} = V_{GS}, I_{DS} = -250 \mu A$
		_	80	100		$V_{GS} = -4.5V$, $I_{D1D2} = -1A$
Static Drain-Source On-Resistance	R _{D1D2(ON)}	_	105	130	mΩ	$V_{GS} = -2.5V$, $I_{D1D2} = -1A$
		_	140	175		$V_{GS} = -1.8V, I_{D1D2} = -1A$
Forward Transfer Admittance	Y _{fs}	_	5.3	_	S	$V_{D1D2} = -10V$, $I_{D1D2} = -1A$
DIODE CHARACTERISTICS						
Diode Forward Voltage (Note 6)	V_{SD}	_	-0.7	-1	V	$V_{GS} = 0V, I_{D1D2} = -1A$
Reverse Recovery Charge	Qrr	_	18	_	nC	$V_{dd} = -9.5V$, $I_F = -1A$,
Reverse Recovery Time	t _{rr}	_	34	_	ns	di/dt = 200A/µs
DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	C _{iss}	_	232	310	pF	\/ 10\/_\/ 0\/
Output Capacitance	Coss	_	107	150	pF	$V_{D1D2} = -10V, V_{GS} = 0V,$ f = 1.0MHz
Reverse Transfer Capacitance	C _{rss}	_	43.5	55	pF	1 - 1.00112
Total Gate Charge (4.5V)	Qg	_	3.3	4.2	nC	
Gate-Source Charge	Q _{gs}	_	0.3	_	nC	$V_{GS} = -4.5V, V_{D1D2} = -10V,$
Gate-Drain Charge	Q _{gd}	_	0.6	_	nC	$I_{D1D2} = -1A$
Gate Charge at V _{th}	Q _{g(th)}	_	0.2	_	nC	
Turn-On Delay Time	t _{D(on)}	_	8.5	_	ns	
Turn-On Rise Time	t _r	_	7.0	_	ns	$V_{D1D2} = -10V, V_{GS} = -4.5V,$
Turn-Off Delay Time	t _{D(off)}	_	47	_	ns	$I_{D1D2} = -1A, R_G = 30\Omega,$
Turn-Off Fall Time	t _f	_	28	_	ns	

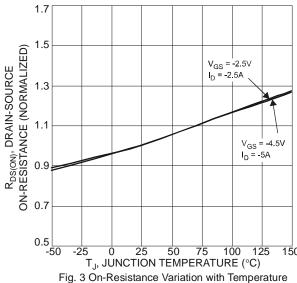
Notes:

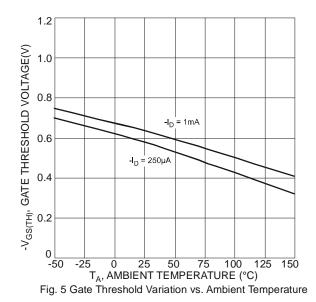
- Device mounted on FR-4 PCB with minimum recommended pad layout.
 Device mounted on FR4 material with 1-inch² (6.45-cm²), 2-oz. (0.071-mm thick) Cu.
- 7. Short duration pulse test used to minimize self-heating effect.
- 8. Guaranteed by design. Not subject to production testing.

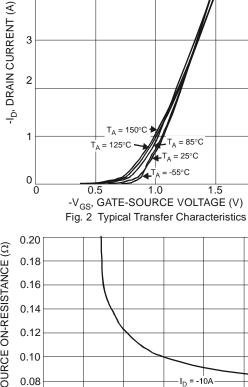
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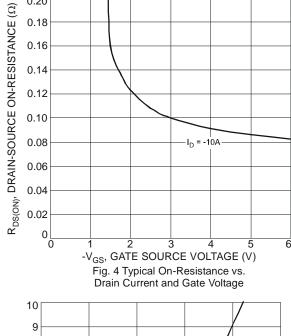








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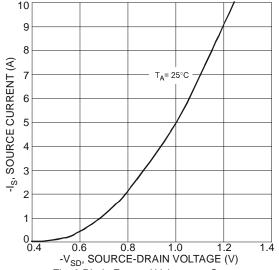
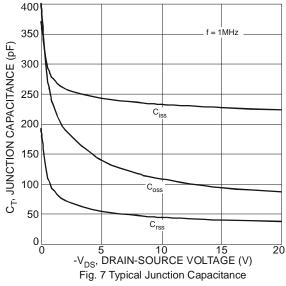
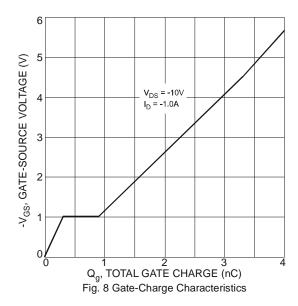
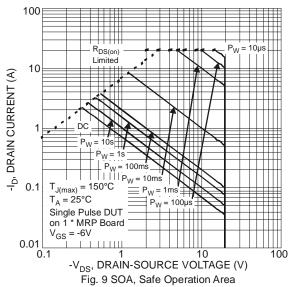


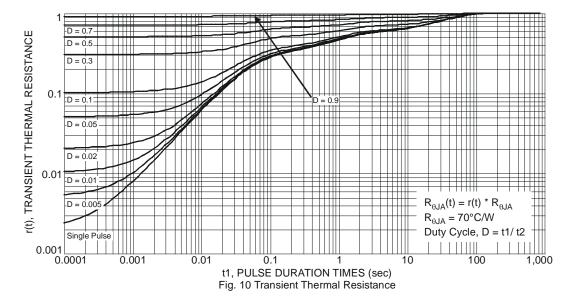
Fig. 6 Diode Forward Voltage vs. Current







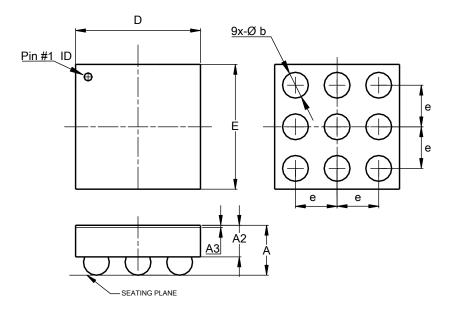






Package Outline Dimensions

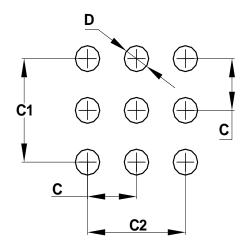
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.



U-WLB1515-9						
Dim	Min	Max	Тур			
Α		0.62				
A2		0.36	0.36			
A3	0.020	0.030	0.025			
b	0.27	0.37	0.32			
D	1.47	1.50	1.49			
Е	1.47	1.50	1.49			
е			0.50			
All Dimensions in mm						

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)			
С	0.50			
C1	1.00			
C2	1.00			
D	0.25			



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